

CLAIMS IN THE CASE

1. (currently amended) A solid containing
 - a) on average per molecule at least least two groups (a) having at least one bond which can be activated with actinic radiation whereby the groups (a) are structurally different from one another and are attached to the parent structure of the solid via urethane groups and
 - b) from 0.01 to 1 mol%, based on the double bonds present of at least one chemically bonded stabilizer, preparable by reacting the starting product in the melt.

Claim 2 (canceled)

3. (currently amended) The solid as claimed in claim 1, characterized in that the bonds which can be activated with actinic radiation comprise carbon-hydrogen single bonds or carbon-carbon, carbon-oxygen, carbon-nitrogen, carbon-phosphorus or carbon-silicon single bonds or double bonds, ~~especially carbon-carbon double bonds.~~
4. (currently amended) The solid as claimed in claim 1 2, characterized in that at least one HALS compounds containing at least on isocyanate-reactive group is used as starting product for introducing the chemically bonded polymerization inhibitor stabilizer (b).
5. (previously presented) The solid as claimed in claim 1, characterized in that the groups (a) are selected from the group containing (meth)acrylate, ethacrylate,

crotonate, cinnamate, vinyl ether, vinyl ester, dicyclopentadienyl, norbornenyl, isoprenyl, isoprenyl, isoprenyl, allyl or butenyl groups; dicyclopentadienyl ether, norbornenyl ether, isoprenyl ether, isopropenyl ether, allyl ether or butenyl ether groups, or dicyclopentadienyl ester, norbornenyl ester, isoprenyl ester, isoprenyl ester, allyl ester or butenyl ester groups.

6. (currently amended) The solid as claimed in claim 5, characterized in that it contains ~~-[lacuna]~~ at least one (meth)acrylate group, ~~especially an acrylate group~~, and at least one group (a) selected from the group containing ethacrylate, crotonate, cinnamate, vinyl ether, vinyl ester, dicyclopentadienyl, norbornenyl, isoprenyl, isopropenyl, ally and butenyl groups; isoprenyl ether, isopropenyl ether, allyl ether and butenyl ether groups, and also isoprenyl ester, isopropenyl ester, allyl ester and butenyl ester groups.
7. (previously presented) The solid as claimed in claim 1, characterized in that it comprises chemically bonded photoinitiators and/or photoco-initiators.
8. (previously presented) The solid as claimed in claim 1, characterized in that it contains functional groups (e) which are able to undergo thermal crosslinking reactions with groups (e) of their own kind and/or with complementary functional groups (f).
9. (previously presented) The solid as claimed in claim 1, characterized in that it is amorphous, partly crystalline, or crystalline.
10. (previously presented) The solid as claimed in claim 1, characterized in that it has a melting range or melting point in the temperature range from 40 to 130°C.

11. (previously presented) The solid as claimed in claim 1, characterized in that it has a melt viscosity at 130° of from 50 to 20 000 mPas.
12. (previously presented) The solid as claimed in claim 1, characterized in that its parent structure is of low molecular mass, oligomeric and/or polymeric.
13. (original) The solid as claimed in claim 12, characterized in that the oligomeric and/or polymeric parent structure contains olefinically unsaturated double bonds.
14. (previously presented) The solid as claimed in claim 12, characterized in that the oligomeric and/or polymeric parent structure is derived from random, alternating and/or block, linear, branched, hyperbranched, dendrimeric and/or comb poly-addition resins, polycondensation resins and/or addition (co)polymers of ethylenically unsaturated monomer.
15. (currently amended) The solid as claimed in claim 14, characterized in that the addition (co)polymers are poly-(meth)acrylates and/or partially hydrolyzed polyvinyl esters and the ~~polyaddition~~ polyaddition resins and/or polycondensation resins are polyesters, alkyds, polyurethanes, polyester-polyurethanes, polylactones, polycarbonates, polyethers, poly-ether-polyesters, epoxy resin-amine adducts, polyureas, polyamides or polyimides especially polyesters, polyester-polyethers, polyurethanes, and polyester-polyurethanes.

Claim 16 (canceled)

17. (currently amended) Coating materials, adhesives or sealing compounds comprising at least one solid as claimed in claim 1.
18. (original) The coating materials, adhesives or sealing compounds as claimed in

claim 17, characterized in that at least one further constituent curable with actinic radiation is present therein.

19. (original) The coating materials, adhesives or sealing compounds as claimed in claim 18, characterized in that the further constituent is selected from the group containing (meth)acryloyl-functional (meth)acrylic copolymers, polyether acrylates, polyester acrylates, unsaturated polyesters, epoxy acrylates, amino acrylates, melamine acrylates, silicone acrylates, and the corresponding methacrylates.
20. (original) The coating materials, adhesives or sealing compounds as claimed in claim 17, characterized in that at least one further additive is present therein.
21. (previously presented) The coating materials, adhesives or sealing compounds as claimed in claim 17, characterized in that at least one further additive is present therein.
22. (previously presented) The coating materials, adhesives or sealing compounds as claimed in claim 17, characterized in that they are present as powders, powder slurries, or in solution or dispersion in organic solvents.

Claim 23 (canceled)

24. (previously presented) A process for producing coatings, adhesive films or seals for primed or unprimed substrates, wherein
 - (1) at least one coating material and/or adhesive and/or sealing compound as claimed in claim 17 in the form of
 - (1.1) a melt,

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- (1.2) a powder,
 - (1.3) a powder slurry or
 - (1.4) a dispersion or a solution in at least one organic solvent is applied to the
primed or unprimed substrate,
 - (2) the resulting powder slurry film (1.3) or the resulting film of a dispersion or a
solution (1.4) is dried or the resulting film of the melt (1.1) is caused to solidify or
is maintained in the melted state by heating,
 - (3) the resulting solid film (1.2), (1.3) or (1.4) is melted by heating, and
 - (4) the melted film which results in process step (2) or (3),
 - (4.1) in the melted state,
 - (4.2) on solidification and/or
 - (4.3) after solidification,
- is cured with actinic radiation.

- 25. (original) The process as claimed in claim 24, characterized in that the film is
thermally cured by heating during or after process step (4).
- 26. (previously presented) The process as claimed in claim 24, characterized in that
heating is carried out with near infrared (NIR) light.
- 27. (previously presented) Coatings, adhesive films or seals on primed or unprimed
substrates, produced by the process as claimed in claim 24.
- 28. (currently amended) Primed and unprimed substrates ~~especially bodies of
automobiles and commercial vehicles, industrial components, including plastic
parts, packaging, coils and electrical components, or furniture, comprising at~~

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least one coating, at ~~least~~ least one adhesive film and/or at least one seal as claimed in claim 27.

29. (new) The solid of claim 3, wherein the bonds are carbon-carbon double bonds.
30. (new) The solid of claim 6, wherein the (meth)acrylate group is an acrylate group.
31. (new) The solid of claim 15, wherein the polyaddition resins and/or polycondensation resins are polyesters, polyester-polyethers, polyurethanes or polyester-polyurethanes.
32. (new) The primed and unprimed substrates of claim 28, which are bodies of automobiles and commercial vehicles, industrial components, plastic parts, packaging, coils, electrical components or furniture.
33. (new) The solid of claim 1, wherein the parent structure is an oligomer and/or a polymer.